

Transformer

| Product Class: | | SMD E5 B82801B**** | | | | | b | | | | |
|---|--|--|---|------------------------|--|--|------------------|----------------------|--|---------------------------------|--|
| Date | | 26.01.2012 | | | | | | | | | |
| IMDS ID | | | | | | | | | | | |
| if available | | | | | | | | | | | |
| Version: | | 10 | | | | J. | _ | | | | |
| Product Part (IMDS: semi component) | S: semi (IMDS: Material) | | Material (Classification) VDA 231 | Substance | | | TMPS**) [wt%] | CAS if applicable | typical mass of material [wt-%] | Traces see 1) | |
| Active Part | Ceramic | | 4B | Manganese Zinc Ferrite | | | 100 | 12645-49-7 | 44.6 | | |
| | Heavy Metal | | 1C | Cu | | 100 | 7440-50-8 | 16.2 | | | |
| | Elastomer | | 2B | Polyurethane (PUR) | | | 100 | 9009-54-5 | 0.9 | | |
| Encapsulation | Thermoplastic | | 2A | Phenolplast | | 35-50 | 9003-35-4 | | | | |
| and | | | | Glass fiber | | 50-65 | 65997-17-3 | 18.5 | | | |
| Mounting | Durome | r | 2C | Epoxy (EP) | | | 100 | 25068-38-6 | 2.9 | | |
| | Thermor | olastic | 2A | Polyimide (PI) | | | 100 | 26298-81-7 | 1.0 | | |
| | Duromer | | 2C | Acrylic polymer | | | 100 | 9017-68-9 | 0.1 | | |
| | Heavy Metal | | 10 | Cu | | | 100 | 7440-50-8 | 14.3 | | |
| | Heavy M | | 10 | Sn | | | 100 | 7440-31-5 | | x | |
| Termination | Heavy Metal | | 10 | Cu | | | 94 | 7440-50-8 | | | |
| | | | 10 | Sn Sn | | | 6 | 7440-31-5 | 1.4 | | |
| | | | 1C | | | | 100 | 7440-31-5 | 0,1 | | |
| | | | | | | | | Sum in total: | 100.0 | | |
| Size W x L x H Weight Part Numbers [max. in mm] [approx. in g] 8.13x7.11x5.08 0.35 B82801B****A*** | | | | | | | | | | | |
| Contact I | Dr. Johann Reindl, MAG EPQM | | | | | Important remarks: | | | | | |
| Division | TDK Electr | ectronics AG, Magnetics Business Group (MAG) | | | | 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906) Traces are | | | | | |
| Address I | Rosenheimer Strasse 116b, 81669 Munich | | | | | product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated | | | | | |
| 1 | Tel: +49 89 54020 3030 mailto: johann.reindl@tdk-electronics.tdk.co | | | atropias telle som | This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are | | | | | | |
| *) others: (not d | eclarable (| or prohibited subs | tances acc. GADSI | | based on our best present knowledge and cannot be regarded as binding statement | | | | | statements | |
| **) typical mass percentage of substance or binding product specifications, unless otherwise explicitly agreed in ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY IN REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPL STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUE HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTAT WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY F | | | | | | | | | | AÎM ANY DR DNTAINED DR | |
| The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8 th , 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment. | | | | | | | | | | | |
| RoHS - Exempt | tions for th | he Product Class | / Product accord | ling to Annex III: | (⊠ va | alid 🛛 not valid) | | | | | |
| ✓ no exemptions; □ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight; □ Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight; □ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight; □ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead); □ Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound; □ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher; □ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC; | | | | | | | | | | | |
| Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages; | | | | | | | | | | | |
| Other Exemption than above | | | | | | | | | | | |